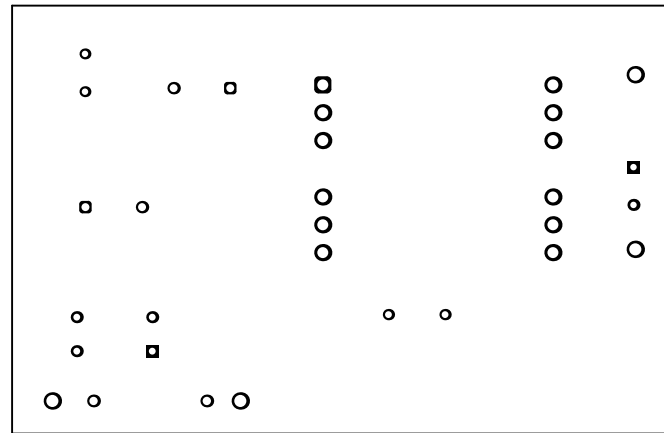
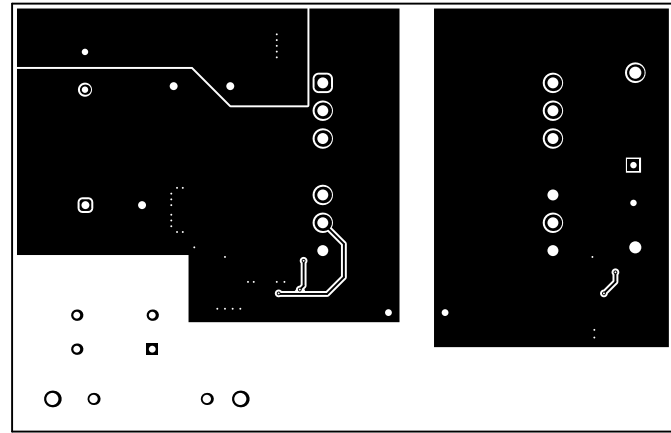


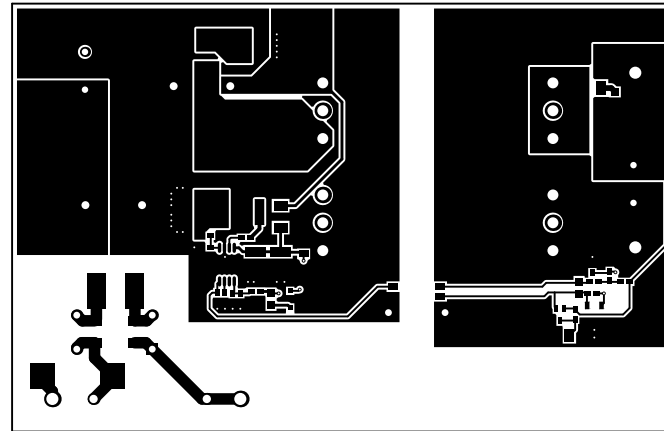
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: N/A		
PLOT NAME = Top Overlay	GENERATED : 8/10/2017	4:16:44 PM	TEXAS INSTRUMENTS



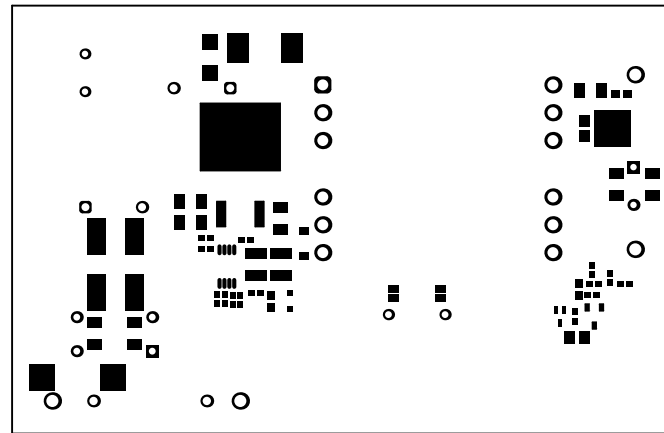
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 8/10/2017 4:16:45 PM	TEXAS INSTRUMENTS	



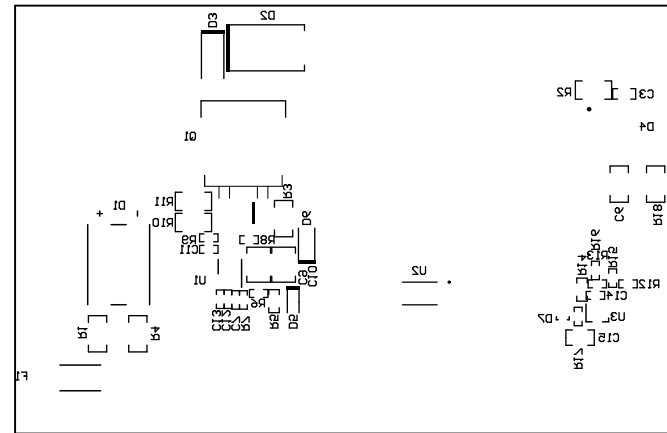
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 8/10/2017 4:16:46 PM	TEXAS INSTRUMENTS	



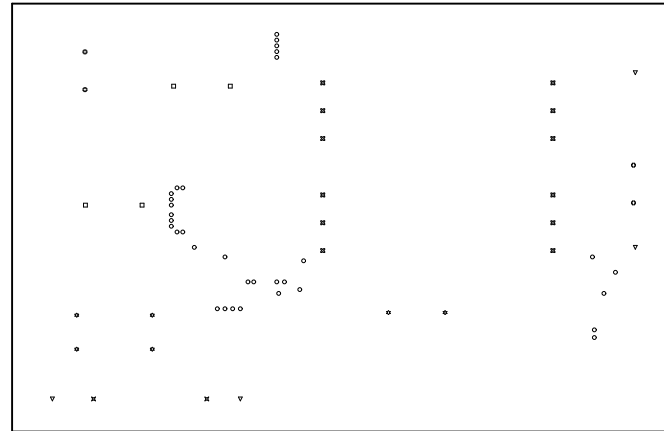
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 8/10/2017 4:16:48 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/10/2017 4:16:49 PM	TEXAS INSTRUMENTS	

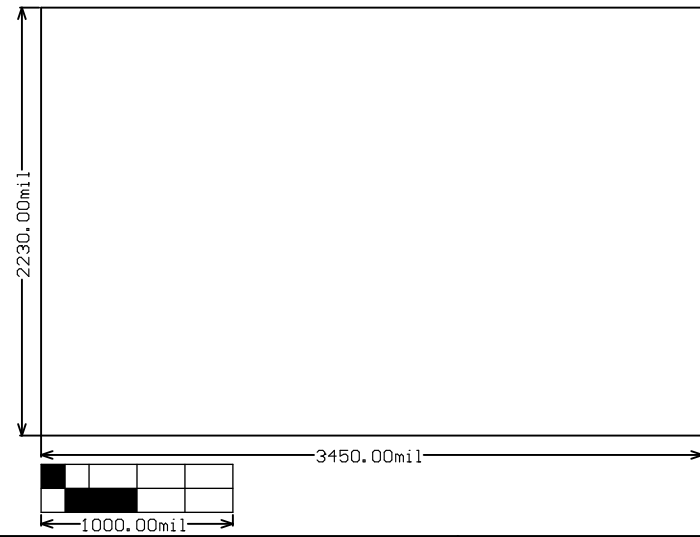


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: N/A		
PLOT NAME = Bottom Overlay	GENERATED : 8/10/2017 4:16:50 PM		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	33	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	6	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	2	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
⊞	12	57.09mil (1.450mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	65 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 8/10/2017	4:16:51 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20815	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 8/10/2017 4:16:53 PM	TEXAS INSTRUMENTS	

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